CCERF	amate	TYPE	SMV0603EDDDDDDDDRR MODE	E	PAGE	1/9
CITA	CITATION			DATE	Feb. 06, 2	2009
SUBJ	IECT		Structure	REV.	C01	
1.	STRUCT	URE				_
NO.	ITE	EM	DESCRIPTION			ļ
1.1	Main M	laterial	Zinc Oxide			
1.2	End terr	mination	Ag/Ni/Sn			
1.3	Pack	aging	Reel			
1.4		es with dard	IEC61000-4-2 level 4			
1.5	Complies Stan	with Ro⊦ dard	IS Yes			
1.6	Lead o	content	< 1000ppm			
1.7		lder prof erature nmend)	le 250 °C			
			L	1.60	0 ± 0.15	
			a W	0.80	0 ± 0.10	
			T(max	.)	0.90	
1.8	1.8 Dimer		a	0.3	3 ± 0.1	
1.0	Dimer	1510115	$\frac{1}{U}$			

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SUBJECT		Electrical Characteristics		REV.	C01	

2. ELECTRICAL CHARACTERISTICS

N0.	ITEM	PERFORMANCE	TEST METHODS
2.0	Standard Conditions		Unless otherwise specified, all tests are made under environmental conditions as given below: Temperature: 5~35°C Relative humidity: 45~85 % RH
2.1	Maximum Allowable Voltage	AC : *(1) V _{rms} DC : *(1) V	Maximum continuous sine wave(RMS) or DC voltage which may be applied.
2.2	Varistor Voltage	V _{0.1mA} : *(1) V	Voltage across the varistor measured at C_{mA} DC.
2.3	Varistor Voltage Temperature Coefficient	0 ~ –0.05 %/°C	<u>VomAalase — VomAalase</u> x <mark>1</mark> VomAalase — X
2.4	Max. Clamping Voltage	* (1) Vat 1 A	Peak voltage across the varistor with a specified peak impulse current of 8x20µs waveform.
2.5	ESD Trigger Voltage (V⊤)	< *(1) ∨	
2.6	Response time	T _{rise} < 1 nS	
2.7	Leakage current	I _{LDC} <*(1)μA I _{LDCA} <*(1)μA	at V1 _m A×80% at V1 _m A×80% (After ESD Test)
2.8	Capacitance	* (1) pF.	Capacitance shall be measured at 1 MHz,1 Vrms max. 0V bias and $20\pm2^{\circ}$ C

*(1) See table 2.1 Electrical Characteristics

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Table 2.1 Electrical Characteristics

Part Number	Maximum Allowable Voltage		Varistor Clamping Trigg		ESD Trigger Voltage (V⊤)	Leakage Current (µA)		Typical Capacitance	
Symbol	AC	DC	V (1mA)	V	V	I_{LDC}	I _{LDCA}	PF(MHz)	Tolerance (%)
0603E0500R2PRR		5		<50	160	0.05	10	0.25	+50/-50
0603E050050PRR	3.3	5	20~30	<55		1	2	4~9	+80/-20
0603E050100NRR	3.3	5	24~36	<65		1	2	10	+30/-30
0603E050220NRR	3.3	5	15~25	<34		1	2	22	+30/-30
0603E050330NRR	3.3	5	15~25	<34		1	2	33	+30/-30
0603E050560NRR	3.3	5	15~25	<36		0.1	2	56	+30/-30
0603E050820NRR	3.3	5	15~25	<34		1	2	82	+30/-30
0603E050101NRR	3.3	5	15~25	<36		1	2	100	+30/-30
0603E120050PRR	8	12	33~50	<85		1	2	5~9	+80/-20
0603E120100NRR	8	12	27~42	<60		0.1	2	10	+30/-30
0603E120220NRR	8	12	20~30	<55		1	2	22	+30/-30
0603E120330NRR	8	12	20~30	<55		1	2	33	+30/-30
0603E120560NRR	8	12	20~30	<55		1	2	56	+30/-30
0603E120820NRR	8	12	20~30	<55		1	2	82	+30/-30
0603E120101NRR	8	12	20~30	<55		1	2	100	+30/-30
0603E2400R05PR		24		<100	350	0.04		0.05	+200/-100
0603E2400R8PRR		24	100~150	<200		0.1	2	0.8~1.5	+80/-20
0603E2402R0PRR		24	120~180	<240		0.1	2	1.5~3.5	+80/-20
0603E2402R8PRR		24	120~180	<240		0.1	2	2~4.5	+80/-20
0603E2402R5PRR	18	24	100~150	<240		0.1	2	2~4.5	+80/-20
0603E240080NRR		24	160	<240		0.1	2	8	+30/-30
0603E240100NRR		24	35.3~42.9	<72		0.1	2	10	+30/-30
0603E240130NRR		24	160	<240		0.1	2	13	+30/-30

* 0603E2400R2PRR : Minimum ESD pulse withstand 2000 times

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3. ENVIRONMENTAL CHARACTERISTICS

No.	Characteristic		Test method and description							
3.1	High Temperature Storage	The specimen shall be subjected to $150 \pm 2^{\circ}$ C for 1000 ± 12 hours in a thermostatic bath without load and then stored at room temperature and humidity for 1 to 2 hours. The change of varistor voltage shall be within 10%.								
		The temperature cycle of specified	Step	Temperature	Period					
		temperature shall be repeated five times	1	-40±3 ℃	30Min±3					
3.2	3.2 Temperature Cycle	and then stored at room temperature and humidity for one or two hours. The	2	Room Temperature	1~2 hours					
		change of varistor voltage shall be within	3	125±2 ℃	30Min±3					
		10% and mechanical damage shall be	4	Room Temperature	1~2 hours					
3.3	High Temperature Load	After being continuously applied the maxin hours, the specimen shall be stored at roo hours, the change of varistor voltage shall	m temp	erature and humidity fo						
3.4	Damp Heat Load/ Humidity Load	The specimen should be subjected to 40 ± maximum allowable voltage applied for 10 and humidity for one or two hours. The cha	00 hour	s, then stored at room t	emperature					
3.5	Low Temperature Storage	The specimen should be subjected to $-40 \pm 2^{\circ}$ C, without load for 500 hours and then tored at room temperature for one or two hours. The change of varistor voltage shall be <i>v</i> ithin 10%								

4. TECHNICAL TERM

No.	Item	Specifications	Description
4.1	Operating Temperature Range	-40°∁ to +85°∁	Operating temperature range without derating.
4.2	Storage Temperature Range	-40℃ to +125℃	Storage temperature range without voltage applied.
4.3	Transient Response Time	< 50 ns	Time lag between application of surge and varistor's "turn-on" conduction action.

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SUBJECT			Sol	dering		REV.	C01	
	der pad	layout C 0.7~1.0	D 0.9~1.2		▲►		-	

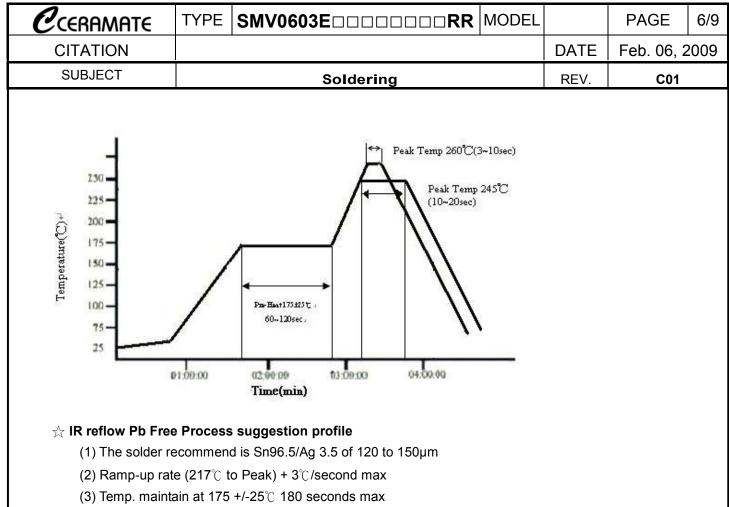
5.2 The SIR test of the solder paste shall be done (Based on JIS-Z-3284)

5.3 Steel plate and foot distance printing

Foot distance printing (mm)	Steel Plate thickness (mm)
> 0.65mm	0.18mm
0.65mm~0.5mm	0.15mm
0.50mm~0.40mm	0.12mm
<=0.40 mm	0.10mm

5.4 IR Soldering

Rapid heating, partial heating or rapid cooling will easily cause defect of the component. So preheating and gradual cooling process is suggested. IR soldering has the highest yields due to controlled heating rates and solder liquids times. Make sure that the element is not 2.4 The IR reflow and temperature of Soldering for Pb Free subjected to a thermal gradient steeper than 4 degrees per second. 2 degrees per second is the ideal gradient. During the soldering process, pre- heating to within 100 degrees of the solders peak temperature is essential to minimize thermal shock.



- (4) Temp. maintain above 217 $^\circ\!\mathbb{C}$ 60-150 seconds
- (5) Peak temperature range <u>245℃</u> +<u>20℃/-10℃</u> time within 5 ℃ of actually peak temperature (tp) 10~20 seconds
- (6) Ramp down rate +6 $^{\circ}$ C/second max.

*Perform adequate test in advance as the reflow temperature profile will vary according to the conditions of the manufacturing process, and the specification of the reflow furnace.

5.5 Resistance to soldering heat-High Temperature Resistance:260°C,10sec-3times.

5.6 Hand Soldering

In hand soldering of the Varistors. Large temperature gradient between preheated the Varistors and the tip of soldering iron may cause electrical failures and mechanical damages such as crackings or breakings of the devices. The soldering shall be carefully controlled and carried out so that the temperature gradient is kept minimum with following recommended conditions for hand soldering.

5.6.1 Recommended Soldering Condition 1

(1) Solder

0.12~0.18mm Thread solder (Sn96.5:Ag3.5) with soldering flux in the core. Rosin-based and non-activated flux is recommended.

(2) Preheating

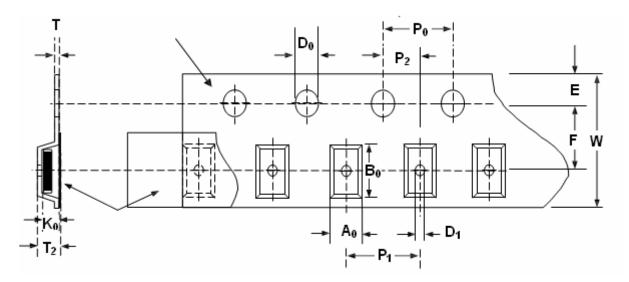
The Varistors shall be preheated so that Temperature Gradient between the devices and the tip of soldering iron is 150° C or below.

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Tempera in advan (4) Cooling After sol 5.6.2 Recommended (1) Solder inc (2) Solder inc electrode 5.7 Post Soldering Clea 5.7.1 Residues of co electrical chara mounted on the affected by the 5.7.2. When an ultras recommended	wer of 20w max with 3mm soldering tip in diameter. ture of soldering iron tip 380°C max,3-5sec (The required a ce on the soldering tip.) lering. The Varistors shall be cooled gradually at room amb Soldering Condition 2 (Without preheating) In tip shall not directly touch to ceramic dielectrics. In tip shall be fully preheated before soldering while soldering of Varistors. In tip soldering fluxes on the PC board after cleaning may cteristic and the reliability (such as humidity resistance)of the board. It shall be confirmed that the characteristic and the applied cleaning conditions. In the other cleaning is applied to the mounted Varistors on PC F for preventing failures or damages of the devices due to the sed by the ultrasonic waves.	ient temperatur ng iron tip to the greatly have i he Varistors wh reliability of th Boards. Follow	re. e external nfluences on nich have bee e devices are	the n e not s are
(1) Freque	d Power 20w/lithr max			

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6. PACKAGING SPECIFICATION

- 6.1 Carrier tape and transparent cover tape should be heat-sealed to carry the products, and the reel should be used to reel the carrier tape.
- 6.2 The adhesion of the heat-sealed cover tape shall be 40 +20/ -15grams.
- 6.3 Both the head and the end portion of the taping shall be empty for reel package and SMT auto-pickup machine. And a normal paper tape shall be connected in the head of taping for the operator to handle



Symbol	A0 ±0.05	B0 ±0.05	K0 ±0.05	T ±0.05	T2 ±0.05	D0 +0.10 -0.05	D1 ±0.05	P1 ±0.10	P2 ±0.10	P0 ±0.10	W ±0.10	E ±0.10	F ±0.05
mm	1.10	1.90	0.95	0.22	1.26	1.56	1.00	4.00	2.00	4.00	8.00	1.75	3.50

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7. REEL DIMENSION													
		••••											
			E →	\backslash									
	В												
				/	/								
							\mathbf{W}_1						
					•	┨╺╾┠⋖──	w ₁						
	I		А		·•								
Symbol	Α	В	С	D	Е	W	W ₁						
Unit(mm)	178±1	60±0.5	13±0.2	21±0.2	2.0±0.5	9±0.5	1.5±0.15	5					
Standard pa	ckaging :	1000 pc	s/Reel.										